Title: Datasheet for LM15851 Customer Contact: PCN Manager Dept: Quality Services Change Type: Wafer Bump Nite Wafer Bump Nite Assembly Process Data Sheet Wafer Bump Nite Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Materials Packing/Shipping/Labeling Test Site Wafer Fab Materials Description of Change: Notification Details Description of Change Wafer Sum Materials Part number change Description of Change: Notification Details Part number change Wafer Fab Process Description of Change Notification Details Part number change Materials Materials Description of Change Exas LM15851 State Materials Other of the product datasheet(s) is being updated as summarized below. Page Page Change from Revision D (July 2015) to Revision E Page Page Changed reset value of address 0x006 from 0x03 to 0x13 in Memory Map table. 43 Changed reset value of address 0x006 from 0x03 to 0x13 in Standard SPI-3.0 Registers table. 51	PCN Number:	20171020000	PCN Date:	October 23, 2	2017	
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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